

Appl. No. 10/008,337
Amendment and/or Response
Reply to Office action of 30 June 2003

Page 6 of 8

REMARKS / DISCUSSION OF ISSUES

Claims 12-24 are pending in the application.

Applicant thanks the Examiner for acknowledging the claim for priority and receipt of certified copies of all the priority documents.

The Examiner is respectfully requested to state whether the drawings are acceptable.

The Office action rejects claims 12-14, 17-20, 23, and 24 under 35 U.S.C. 102(b) over Harari (USP 5,786,988). The applicant respectfully traverses this rejection.

Independent claims 12, 17, 23, and 24 each recite an electronic device having a layer of rigid material with electronic components mounted directly thereon. Harari teaches a layer of rigid material 133 with openings 135 within which electronic components 33, 153, 155 are placed. As illustrated in each of Harari's FIGs. 10B, 11B, and 12B, the electronic components 33, 153, 155 are not mounted on the rigid material 133.

Because Harari does not teach an electronic device having a layer of rigid material with electronic components mounted directly thereon, as specifically claimed in each of claims 12, 17, 23, and 24, upon which each of the other rejected claims depend, the applicant respectfully requests the Examiner's reconsideration of the rejection of claims 12-14, 17-20, 23, and 24 under 35 U.S.C. 102(b) over Harari.

The Office action rejects claims 12-13, 16-19, and 22-24 under 35 U.S.C. 102(b) over Li et al. (USP 5,998,738, hereinafter Li). The applicant respectfully traverses this rejection.

Independent claims 12, 17, 23, and 24 each recite an electronic device having a layer of rigid material with electronic components mounted directly thereon. Li uses the conventional means of forming an flexible circuit by mounting electronic components 26 upon a flexible substrate 18. Li teaches bonding the flexible substrate 18 to a bendable base plate 12 to create a rigid device to which a connector 36 can be attached. Li does not teach mounting electrical components directly upon a layer of rigid material.

Because Li does not teach an electronic device with electrical components mounted directly upon a layer of rigid material, as specifically claimed in each of claims 12, 17, 23, and 24, upon which each of the other rejected claims depend, the applicant respectfully

Appl. No. 10/008,337
Amendment and/or Response
Reply to Office action of 30 June 2003

Page 7 of 8

requests the Examiner's reconsideration of the rejection of claims 12-13, 16-19, and 22-24 under 35 U.S.C. 102(b) over Li.

The Office action rejects claims 17, 20, and 24 under 35 U.S.C. 102(b) over Ocken et al. (USP 5,179,501, hereinafter Ocken). The applicant respectfully traverses this rejection.

Independent claims 17 and 24 each recite an electronic device having a layer of rigid material with electronic components mounted directly thereon. As in Li, above, Ocken uses the conventional means of forming an flexible circuit by mounting electronic components 26, 28 upon a flexible substrate 34. Ocken teaches bonding the flexible substrate 34 to a metal plate 24, 32 to create a heat sink for the components 26, 28. Ocken does not teach mounting electrical component directly upon a layer of rigid material.

Additionally, claims 17 and 24 each claim a rigid layer (singular) with *contiguous* regions that are bridged with flexible connectors. Ocken teaches two separate and disjoint rigid metal plates 24 and 32, and does not teach a single rigid layer with contiguous regions that are bridged by flexible connectors.

Because Ocken does not teach an electronic device with electrical components mounted directly upon a single layer of a rigid material with contiguous regions that are bridged by flexible connectors, as specifically claimed in each of claims 24 and 17, upon which claim 20 depends, the applicant respectfully requests the Examiner's reconsideration of the rejection of claims 17, 20, and 24 under 35 U.S.C. 102(b) over Ocken.

The Office action rejects claims 17, 22, and 24 under 35 U.S.C. 102(e) over Schmich (USP 6,396,709). The applicant respectfully traverses this rejection.

Independent claims 17 and 24 each claim an electronic device with a rigid layer (singular) having *contiguous* regions that are bridged with flexible connectors.

Schmich teaches a flexible connection between two separate and disjoint rigid circuit boards 2 and 3. As illustrated in Schmich's FIGs. 1, 3, 4, and 5, circuit boards 2 and 3 are not regions of a single rigid layer of an electronic device, and are not contiguous.

Because Schmich does not teach an electronic device having a rigid layer with contiguous regions that are bridged with flexible connectors, as specifically claimed in claims 24 and 17, upon which claim 22 depends, the applicant respectfully requests the Examiner's

Appl. No. 10/008,337
Amendment and/or Response
Reply to Office action of 30 June 2003

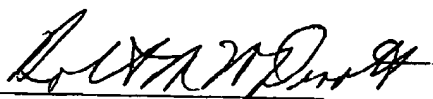
Page 8 of 8

reconsideration of the rejection of claims 17, 22, and 24 under 35 U.S.C. 102(e) over Schmich.

The Office action rejects claims 15 and 21 under 35 U.S.C. 103(a) over Harari, Li, Ocken, or Schmich, and Mitchell (USP 4,605,471). The applicant respectfully traverses this rejection, based on the remarks above regarding Harari, Li, Ocken, and Schmich and claims 12 and 17, upon which claims 15 and 21 depend.

In view of the foregoing, the applicant respectfully requests that the Examiner withdraw the rejections of record, allow all the pending claims, and find the application to be in condition for allowance. If any points remain in issue that may best be resolved through a personal or telephonic interview, the Examiner is respectfully requested to contact the undersigned at the telephone number listed below.

Respectfully submitted,



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